

NEWS RELEASE

Christina Sanchez or Beth Smith
The Simon Group
Phone: (215) 453-8700
Fax: (215) 453-1670
E-mail: publicrelations@simongroup.com



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New Fine Pitch Bump Adapters from Aries Enable Use of Alternate ICs on PCBs Originally Designed for TSSOPs and QFP Packages

Bristol, Pa. June 2009 – Aries Electronics, an international manufacturer of standard, programmed and custom interconnection products, has launched a new series of adapters that enable the use of virtually any SMT IC device on a pitch of 0.4 mm or higher to PC boards on 0.5 mm pitch. These are ideally suited to adapting an IC device to some of the more popular TSSOP and QFP packages on 0.5 mm pitch. The unique Fine Pitch Bump Adapters, an expansion to Aries' line of Correct-A-Chip Adapters, save designers significant time and money by eliminating the need for costly engineering rework.

This adapter will enable the user to solder a BGA or other SMT device to pads on the component side of the adapter, which will then connect through the adapter to the 0.5 mm pitch raised connection pads (up to 0.010") on the bottom. The connection scheme comes standard in a pin 1-to-pin 1 routing, but can easily be customized to accommodate virtually any connection requirement.

The Aries Fine Pitch Bump Adapter boards are fabricated from 0.032" thick FR4 or Rogers 370 HR, with 1/2 oz. copper traces on both sides. The NSMD pads are finished with ENIG. The adapters operate at up to 221°F (105°C) for FR4 versions and 226°F (130°C) for the lead-free version.

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Fine Pitch Bump Adapters are available in a panelized form for easy pick-and-place assembly of the new device, as an adapter only, or as a complete, turn-key solution with devices mounted. Aries specializes in custom design and production. In addition to standard products, special materials, platings, sizes and configurations can be furnished depending on quantity.

Pricing is dependent on application and quantity, but typically starts at \$10 each in quantities of 250 pieces. Delivery is four to six weeks ARO.

For additional information, contact Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810; Tel: 215-781-9956; Fax: 215-781-9845; Email: info@arieselec.com; Web: www.arieselec.com, Data sheet #18107— <http://www.arieselec.com/products/18107.pdf>. Europe Email: europe@arieselec.com.

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READER SERVICE INQUIRIES: Please forward all reader service inquiries to Frank Folmsbee, Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810.

UPCOMING TRADESHOW: SEMICON West; Booth # 435 South Hall; July 14-16, 2009, San Francisco, Calif.

EDITORS NOTE: Headquartered in Bristol, Pa., Aries Electronics Inc., manufactures an extremely broad range of custom and standard interconnection and packaging products for electronics. Industry leading products include Zero Insertion Force (ZIF) test sockets for DIP, PGA, PLCC and SOIC devices; the Correct-A-Chip™ product line of "intelligent connectors"; adapters and connectors; several patented concepts for BGA (ball grid array) and LGA (land grid array) sockets; and an extensive array of high frequency test and burn in sockets. The company also specializes in meeting custom requirements for its customers.